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EFS ID: 64277

Application ID: 10766046



Title of Invention: LEADFRAME TYPE
SEMICONDUCTOR PACKAGE
HAVING REDUCED INDUCTANCE
AND ITS MANUFACTURING
METHOD

First Named Inventor: GI KIM

Domestic/Foreign Application: Domestic Application

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Statement

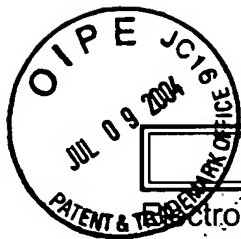
Filing Type:

Confirmation number: 2288

Attorney Docket Number: AMKOR099A


Total Fees Authorized:

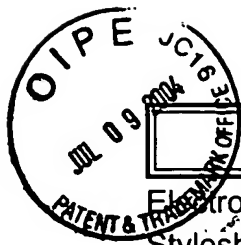
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TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	LEADFRAME TYPE SEMICONDUCTOR PACKAGE HAVING REDUCED INDUCTANCE AND ITS MANUFACTURING METHOD									
Application Number: 10/766046 										
Date: 2004-01-28										
First Named Applicant: GI JEONG KIM										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney		
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Documents being submitted	Files									
us-ids	ids3-usidst.xml									
	us-ids.dtd									
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Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of
Invention.

LEADFRAME TYPE SEMICONDUCTOR PACKAGE
HAVING REDUCED INDUCTANCE AND ITS
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Application Number: 10/766046
Confirmation Number: 2288
First Named Applicant: GI KIM
Attorney Docket Number: AMKOR099A
Art Unit: 2613

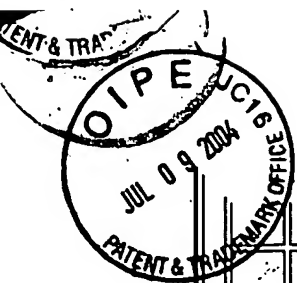


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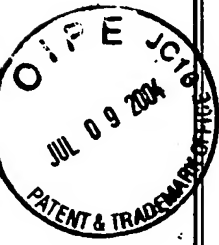
US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date